WM2016 Conference Panel Report

PANEL SESSION 65:	Worldwide challenges in Radioactive Material Packaging
Co-Chairs:	Paul Jones, Ameriphysics Karlan Richards, Bechtel National Inc.
Panel Reporter:	Karlan Richards, Bechtel National Inc.

Panelists:

- 1. Dean Ricker, Vice President of Sales, Skolnik Industries, Inc.
- 2. Bill Smart, Director of Nuclear Sales, PacTec Inc
- 3. **Scott Dempsey,** *Vice President/Director of Sales & Marketing, MHF Services, an Energy Solutions Company*
- 4. Holger Ruechel, Eisenwerk Bassum m.b.H.

This panel focused on challenges for fabricators of radioactive material packaging. Worldwide companies are encouraged to participate. Participants will provide their perspectives and suggestions on how to increase efficiencies through eliminating inconsistencies between specifications and other requirements in order to provide products at a reasonable cost, and enhance communication to enable better service

Summary of Presentations

Each panelist gave a short summary of their company prior to digging into the issues.

One major issue that all the container fabricators have is all the audits that are performed on them by DOE contractors. It appears that each different site wants to perform their individual audits instead of counting on the TCAP audits that are performed by DOE headquarters.

However, one of the fabricators discussed how many audits they had participated in with no findings until one which was conducted recently. There was a finding that resulted in getting an interpretation from DOT that resulted in a revision to the way they performed their stack test for liquid rated drums. They had great support from DOE in getting this issue resolved quickly. Innovations in packaging were discussed with many of the new and improved flexible packaging being introduced to the group. One unique innovation was, the use of super sack packaging for emergency levy repairs. Germany is also creating some custom packages that are very unique to the industry. The design, type testing, and manufacturing responsibilities are as rigid in Germany as in the US.

Some of the issues that were discussed were:

- Packaging specs that require significant vendor investment for small purchases.
- Packaging specs that do not match RFP requests.
- Packaging specs that are not aligned from one request to another.
- Change in budget to actual RFP

The bottom line with these packaging issues is that you need to get your manufacturer involved on the front end. They can help you.

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